

25th International Conference on Electronic Packaging Technology August 07 to 09, 2024, Tianjin, China http://www.icept.org

Speech subject: Low Temperature Sintering of Nanosilver Paste for High Temperature Electronic Package

Speech leader: Yunhui Mei, Executive Vice President of School of Electrical Engineering Tiangong University

Speech Description/Objective:

Speech Outline:

Who Should Attend:

.

Introduction of Speaker:

Yunhui Mei, Professor, Supervisor, Dean of the School of Science and Technology, Executive Vice President of School of Electrical Engineering Tiangong University. He has been engaged in the research of power electronic device packaging and reliability for a long time. In recent years, he has presided over nearly 30 enterprise cooperation projects, such as the 'National Excellent Young Scientists Fund', Tianjin "Science Fund for Distinguished Young Scholars", National Fund Project, National Pre-research Project, "XX Action" Project, Aviation Fund, Huawei, NIO, Inovance Technology Co., Ltd. and so on. He has also participated in key projects of the National Fund, 863 Project, etc. He is serving as a director of the China Power Supply Society, deputy director of the Component Committee, IEEE Senior Member, editorial board member of the Journal of Power Supply, and deputy chairman of the Tianjin Power Supply Society. He has published over 150 academic papers, including 104 SCI papers and 29 granted invention patents, He has won the IEEE CPMT Young Award, the First Prize of the Technology Invention Award of the China Power Supply Society, the First Prize of the Technology Invention Award of the China Electrical Engineering Society, and the First Prize of the Tianjin Technology Invention Award, Henry Fok Education Fund of the Ministry of Education, Science and Technology Award for Youth in Colleges and Universities, IEEE International Power Electronics Annual Conference APEC Best Presentation Award, National Third Generation Semiconductor industry Technology Innovation Strategic Alliance (CASA)'Special Contribution Award', etc.